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Global CSP Package eMMC Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global CSP Package eMMC market size is expected to reach $ 14481 million by 2032, rising at a market growth of 2.6% CAGR during the forecast period (2026-2032).

CSP Package eMMC refers to an embedded non-volatile storage device that integrates NAND flash memory, an eMMC controller, firmware and flash-management functions within a compact chip-scale BGA package. The device connects directly to a host processor through the standardized eMMC interface and internally performs error correction, bad-block management, wear leveling, logical address translation, background operations and other NAND management functions, thereby reducing host-side storage-management complexity. Current commercial products are primarily based on the eMMC 5.1 specification and HS400 transfer mode, with 153-ball BGA/FBGA remaining the mainstream package configuration alongside 100-ball BGA and smaller form-factor packages for space-constrained designs. Product portfolios span multiple storage densities and are commonly differentiated into commercial, industrial and automotive grades according to operating temperature, endurance, NAND configuration, firmware strategy, reliability requirements and product-lifecycle support. CSP Package eMMC is widely used in smartphones and tablets, smart televisions and set-top boxes, networking and surveillance equipment, smart-home devices, industrial and IoT systems, medical electronics and automotive applications where compact size, low power consumption, mature interface compatibility and cost efficiency are important.

Key Findings

eMMC 5.1 remains the mainstream specification for CSP Package eMMC, with 153-ball BGA continuing as the dominant package format

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Demand is gradually shifting from premium mobile devices toward automotive, industrial, IoT, networking and smart-home applications

Industrial and automotive grades are gaining importance as customers prioritize endurance, wide-temperature operation, stable BOMs and long product lifecycles

Supply remains led by NAND manufacturers, while independent storage suppliers compete through controllers, firmware, packaging, testing and customization

Market Trends

The CSP Package eMMC market is moving from a consumer-electronics-led growth model toward a more diversified embedded-storage structure. High-performance smartphones and premium mobile devices continue to migrate toward UFS, reducing the strategic importance of eMMC in applications where interface bandwidth is a primary requirement. At the same time, eMMC 5.1 remains deeply embedded in mature processor platforms used in smart televisions, set-top boxes, networking equipment, surveillance systems, industrial controllers, IoT terminals and automotive electronics. Product development is increasingly focused on reliability rather than interface-speed expansion, including wider operating-temperature ranges, improved endurance, health monitoring, optimized firmware, fixed-BOM programs and longer lifecycle support. Standard 153-ball packages continue to represent the mainstream configuration, while compact BGA designs are gaining relevance in space-constrained embedded products. The long-term direction of the market is therefore characterized by declining dependence on premium consumer electronics and increasing concentration on cost-sensitive, long-lifecycle and high-reliability applications.

Market Dynamics

Drivers

Demand for CSP Package eMMC is supported by the large installed base of processors and embedded platforms designed around the mature eMMC interface. Compared with higher-performance embedded-storage architectures, eMMC offers lower implementation complexity, established software compatibility, compact PCB design and competitive system cost. These characteristics remain important in smart-home products, networking equipment, surveillance devices, industrial control systems, IoT

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terminals and selected automotive electronics, where storage performance requirements are moderate but reliability, power consumption and lifecycle stability are critical.

Restraints

The main structural restraint is the continued substitution of eMMC by UFS in performance-sensitive applications. As application processors support faster storage interfaces and software workloads become more data intensive, high-end smartphones, advanced tablets and selected automotive computing platforms increasingly prefer UFS. The mature nature of eMMC also limits opportunities for major interface-level differentiation, while NAND price cycles can compress margins for independent suppliers that rely on externally sourced flash memory.

Opportunities

The strongest opportunities are emerging in industrial, automotive and long-lifecycle embedded applications where customers increasingly require wide-temperature operation, controlled firmware, stable component configurations and extended supply commitments. Additional opportunities exist in compact eMMC packages for small embedded devices, localized supply chains in China and other Asian manufacturing markets, and customized managed-NAND products designed for industrial controllers, gateways, cameras, edge devices and specialized electronics. These segments provide greater scope for differentiation than standardized consumer-grade products.

Challenges

Suppliers must manage simultaneous pressure from NAND supply volatility, product qualification requirements and technology substitution. Industrial and automotive customers typically require longer validation cycles and stronger reliability guarantees, increasing engineering and inventory commitments. Independent storage suppliers also need sustained capabilities in controller design, firmware optimization, NAND qualification, packaging and failure analysis to compete effectively. As basic consumer-grade eMMC becomes increasingly standardized, maintaining differentiation without excessive cost becomes a central challenge for smaller suppliers.

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Industry Chain Analysis

The upstream CSP Package eMMC industry chain consists primarily of NAND flash wafers and dies, storage controllers, firmware technologies, packaging substrates and related semiconductor materials. NAND represents the largest underlying hardware cost and has a major influence on product pricing and profitability because flash-memory pricing follows cyclical supply-demand conditions. Controller architecture and firmware determine important managed-storage capabilities such as error correction, wear leveling, bad-block management, performance consistency, data retention and device-health management. Packaging and testing provide the physical integration required to combine NAND, controller and associated components into compact BGA-based devices.

The midstream segment integrates NAND resources, controller technology, firmware, packaging and testing into qualified eMMC products and is divided between vertically integrated NAND manufacturers and independent embedded-storage suppliers. The downstream market consists of consumer-electronics manufacturers, networking and surveillance equipment vendors, industrial automation companies, IoT device manufacturers, medical-electronics suppliers and automotive electronics companies. Value creation is increasingly shifting from basic storage capacity toward NAND supply security, firmware reliability, lifecycle management, qualification support and application-specific customization, particularly in industrial and automotive applications.

Segment Insights

By capacity, the current CSP Package eMMC market is concentrated around mainstream embedded-storage densities spanning approximately 16GB to 128GB, while lower-capacity products continue to serve cost-sensitive and legacy embedded platforms and higher-capacity products address selected applications requiring greater local storage. By package configuration, standard 153-ball BGA/FBGA remains the principal commercial format because of its mature ecosystem and broad processor compatibility, while 100-ball and compact BGA packages address designs with tighter PCB-space constraints.

By product grade, commercial-grade products continue to account for the broadest range of volume applications, while industrial-grade and automotive-grade products are becoming increasingly important from a value perspective. These higher-reliability segments require wider operating-temperature ranges, stronger endurance, controlled firmware and longer product lifecycles. By application, smartphones and tablets remain

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an established demand base, but the more attractive structural opportunities are increasingly found in smart televisions and set-top boxes, networking and surveillance, industrial and IoT equipment and automotive electronics.

Downstream Market Opportunities

Downstream opportunities are increasingly concentrated in applications where customers value stable platforms and lifecycle support more than maximum storage-interface performance. Smart televisions, set-top boxes, routers, gateways and surveillance devices continue to provide a broad demand base because eMMC offers sufficient performance at competitive system cost. Industrial automation, IoT edge devices and automotive electronics provide stronger opportunities for product differentiation, as these applications place greater emphasis on endurance, temperature tolerance, data integrity and long-term availability. Automotive clusters, infotainment systems, telematics units and embedded control devices are particularly relevant for suppliers capable of meeting stricter reliability and qualification requirements.

Regional Insights

Asia-Pacific represents the center of the global CSP Package eMMC supply chain, supported by the concentration of NAND manufacturing, semiconductor packaging, storage-controller development and electronics production in South Korea, Japan, China and Taiwan. The region also represents the principal production base for many downstream consumer, industrial and automotive electronics products. China has become one of the most active markets for embedded-storage localization, with domestic suppliers expanding capabilities in controller development, firmware, packaging, testing and product qualification rather than competing only through low-cost assembly.

North America remains important through major semiconductor and embedded-storage suppliers as well as demand from industrial, networking, automotive and technology customers. Europe represents a smaller volume market but has greater relative importance in industrial and automotive applications, where local supply, reliability, product longevity and qualification support are valued. Japan and South Korea retain significant influence through their established NAND technology and semiconductor manufacturing capabilities, while Taiwan maintains a broad ecosystem of storage-controller and industrial-storage suppliers.

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Competitive Landscape Analysis

The CSP Package eMMC market has a two-layer competitive structure. Global NAND manufacturers occupy the leading position through advantages in flash-memory technology, wafer supply, manufacturing scale, cost control and global customer qualification, while independent embedded-storage suppliers compete through controller integration, firmware optimization, NAND sourcing, packaging and testing, industrial-grade design and customer-specific support. Competition in mainstream consumer-grade eMMC is relatively standardized and increasingly cost driven, whereas industrial and automotive segments provide greater room for differentiation through endurance, wide-temperature capability, fixed-BOM strategies, health monitoring, lifecycle management and long-term supply commitments. Chinese suppliers are expanding from conventional packaging and module-oriented activities toward controller, firmware and integrated storage-product development, gradually strengthening local supply capabilities. Over the longer term, competitive intensity is expected to shift away from interface-speed competition and toward supply reliability, firmware capability, application qualification and lifecycle services as UFS continues to absorb performance-oriented applications while eMMC remains concentrated in mature, cost-sensitive and high-reliability embedded platforms.

Report Scope

This report studies the global CSP Package eMMC production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for CSP Package eMMC and provides market size (US$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of CSP Package eMMC that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global CSP Package eMMC total production and demand, 2021-2032, (Million Units)

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Global CSP Package eMMC total production value, 2021-2032, (USD Million)

Global CSP Package eMMC production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Million Units), (based on production site)

Global CSP Package eMMC consumption by region & country, CAGR, 2021-2032 & (Million Units)

U.S. VS China: CSP Package eMMC domestic production, consumption, key domestic manufacturers and share

Global CSP Package eMMC production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Million Units)

Global CSP Package eMMC production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Million Units)

Global CSP Package eMMC production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Million Units)

This report profiles key players in the global CSP Package eMMC market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Samsung Electronics, SK hynix, Kioxia, Sandisk, Micron Technology, Yangtze Memory Technologies, Longsys, Kingston Technology, Silicon Motion, Macronix, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World CSP Package eMMC market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US$

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Millions), volume (production, consumption) & (Million Units) and average price (US$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global CSP Package eMMC Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Market Segmentation

Global CSP Package eMMC Market, Segmentation by Type:

8GB and Below

16GB

32GB

64GB

128GB

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256GB and Above

Global CSP Package eMMC Market, Segmentation by Package Configuration:

Standard 153-ball BGA

Compact BGA

100-ball BGA

Other

Global CSP Package eMMC Market, Segmentation by Product Grade:

Commercial Grade

Industrial Grade

Automotive Grade

Global CSP Package eMMC Market, Segmentation by Application:

Smartphones & Tablets

Smart TV & Set-top Boxes

Networking & Surveillance

Industrial & IoT

Automotive Electronics

Other

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Companies Profiled:

Samsung Electronics

SK hynix

Kioxia

Sandisk

Micron Technology

Yangtze Memory Technologies

Longsys

Kingston Technology

Silicon Motion

Macronix

BIWIN

Rayson

HIKSEMI

ADATA Technology

Apacer Technology

Transcend Information

ATP Electronics

Greenliant

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Swissbit

HOSIN Global Electronics

SCY

KOWIN Technology

Key Questions Answered

1. How big is the global CSP Package eMMC market?
2. What is the demand of the global CSP Package eMMC market?
3. What is the year over year growth of the global CSP Package eMMC market?
4. What is the total value of the global CSP Package eMMC market?
5. Who are the Major Players in the global CSP Package eMMC market?
6. What are the growth factors driving the market demand?

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Contents

1 SUPPLY SUMMARY

1.1 CSP Package eMMC Introduction
1.2 World CSP Package eMMC Supply & Forecast
  1.2.1 World CSP Package eMMC Production Value (2021 & 2025 & 2032)
  1.2.2 World CSP Package eMMC Production (2021-2032)
  1.2.3 World CSP Package eMMC Pricing Trends (2021-2032)
1.3 World CSP Package eMMC Production by Region (Based on Production Site)
  1.3.1 World CSP Package eMMC Production Value by Region (2021-2032)
  1.3.2 World CSP Package eMMC Production by Region (2021-2032)
  1.3.3 World CSP Package eMMC Average Price by Region (2021-2032)
  1.3.4 North America CSP Package eMMC Production (2021-2032)
  1.3.5 Europe CSP Package eMMC Production (2021-2032)
  1.3.6 China CSP Package eMMC Production (2021-2032)
  1.3.7 Japan CSP Package eMMC Production (2021-2032)
  1.3.8 South Korea CSP Package eMMC Production (2021-2032)
1.4 Market Drivers, Restraints and Trends
  1.4.1 CSP Package eMMC Market Drivers
  1.4.2 Factors Affecting Demand
  1.4.3 CSP Package eMMC Major Market Trends

2 DEMAND SUMMARY

2.1 World CSP Package eMMC Demand (2021-2032)
2.2 World CSP Package eMMC Consumption by Region
  2.2.1 World CSP Package eMMC Consumption by Region (2021-2026)
  2.2.2 World CSP Package eMMC Consumption Forecast by Region (2027-2032)
2.3 United States CSP Package eMMC Consumption (2021-2032)
2.4 China CSP Package eMMC Consumption (2021-2032)
2.5 Europe CSP Package eMMC Consumption (2021-2032)
2.6 Japan CSP Package eMMC Consumption (2021-2032)
2.7 South Korea CSP Package eMMC Consumption (2021-2032)
2.8 ASEAN CSP Package eMMC Consumption (2021-2032)
2.9 India CSP Package eMMC Consumption (2021-2032)

3 WORLD MANUFACTURERS COMPETITIVE ANALYSIS

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info@marketpublishers.com

3.1 World CSP Package eMMC Production Value by Manufacturer (2021-2026)
3.2 World CSP Package eMMC Production by Manufacturer (2021-2026)
3.3 World CSP Package eMMC Average Price by Manufacturer (2021-2026)
3.4 CSP Package eMMC Company Evaluation Quadrant
3.5 Industry Rank and Concentration Rate (CR)
3.5.1 Global CSP Package eMMC Industry Rank of Major Manufacturers
3.5.2 Global Concentration Ratios (CR4) for CSP Package eMMC in 2025
3.5.3 Global Concentration Ratios (CR8) for CSP Package eMMC in 2025
3.6 CSP Package eMMC Market: Overall Company Footprint Analysis
3.6.1 CSP Package eMMC Market: Region Footprint
3.6.2 CSP Package eMMC Market: Company Product Type Footprint
3.6.3 CSP Package eMMC Market: Company Product Application Footprint
3.7 Competitive Environment
3.7.1 Historical Structure of the Industry
3.7.2 Barriers of Market Entry
3.7.3 Factors of Competition
3.8 New Entrant and Capacity Expansion Plans
3.9 Mergers, Acquisition, Agreements, and Collaborations

4 UNITED STATES VS CHINA VS REST OF THE WORLD

4.1 United States VS China: CSP Package eMMC Production Value Comparison
4.1.1 United States VS China: CSP Package eMMC Production Value Comparison (2021 & 2025 & 2032)
4.1.2 United States VS China: CSP Package eMMC Production Value Market Share Comparison (2021 & 2025 & 2032)
4.2 United States VS China: CSP Package eMMC Production Comparison
4.2.1 United States VS China: CSP Package eMMC Production Comparison (2021 & 2025 & 2032)
4.2.2 United States VS China: CSP Package eMMC Production Market Share Comparison (2021 & 2025 & 2032)
4.3 United States VS China: CSP Package eMMC Consumption Comparison
4.3.1 United States VS China: CSP Package eMMC Consumption Comparison (2021 & 2025 & 2032)
4.3.2 United States VS China: CSP Package eMMC Consumption Market Share Comparison (2021 & 2025 & 2032)
4.4 United States Based CSP Package eMMC Manufacturers and Market Share, 2021-2026
4.4.1 United States Based CSP Package eMMC Manufacturers, Headquarters and

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Production Site (States, Country)
4.4.2 United States Based Manufacturers CSP Package eMMC Production Value (2021-2026)
4.4.3 United States Based Manufacturers CSP Package eMMC Production (2021-2026)
4.5 China Based CSP Package eMMC Manufacturers and Market Share
4.5.1 China Based CSP Package eMMC Manufacturers, Headquarters and Production Site (Province, Country)
4.5.2 China Based Manufacturers CSP Package eMMC Production Value (2021-2026)
4.5.3 China Based Manufacturers CSP Package eMMC Production (2021-2026)
4.6 Rest of World Based CSP Package eMMC Manufacturers and Market Share, 2021-2026
4.6.1 Rest of World Based CSP Package eMMC Manufacturers, Headquarters and Production Site (State, Country)
4.6.2 Rest of World Based Manufacturers CSP Package eMMC Production Value (2021-2026)
4.6.3 Rest of World Based Manufacturers CSP Package eMMC Production (2021-2026)

5 MARKET ANALYSIS BY TYPE

5.1 World CSP Package eMMC Market Size Overview by Type: 2021 VS 2025 VS 2032
5.2 Segment Introduction by Type
5.2.1 8GB and Below
5.2.2 16GB
5.2.3 32GB
5.2.4 64GB
5.2.5 128GB
5.2.6 256GB and Above
5.3 Market Segment by Type
5.3.1 World CSP Package eMMC Production by Type (2021-2032)
5.3.2 World CSP Package eMMC Production Value by Type (2021-2032)
5.3.3 World CSP Package eMMC Average Price by Type (2021-2032)

6 MARKET ANALYSIS BY PACKAGE CONFIGURATION

6.1 World CSP Package eMMC Market Size Overview by Package Configuration: 2021 VS 2025 VS 2032
6.2 Segment Introduction by Package Configuration

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6.2.1 Standard 153-ball BGA
6.2.2 Compact BGA
6.2.3 100-ball BGA
6.2.4 Other
6.3 Market Segment by Package Configuration
6.3.1 World CSP Package eMMC Production by Package Configuration (2021-2032)
6.3.2 World CSP Package eMMC Production Value by Package Configuration (2021-2032)
6.3.3 World CSP Package eMMC Average Price by Package Configuration (2021-2032)

7 MARKET ANALYSIS BY PRODUCT GRADE

7.1 World CSP Package eMMC Market Size Overview by Product Grade: 2021 VS 2025 VS 2032
7.2 Segment Introduction by Product Grade
7.2.1 Commercial Grade
7.2.2 Industrial Grade
7.2.3 Automotive Grade
7.3 Market Segment by Product Grade
7.3.1 World CSP Package eMMC Production by Product Grade (2021-2032)
7.3.2 World CSP Package eMMC Production Value by Product Grade (2021-2032)
7.3.3 World CSP Package eMMC Average Price by Product Grade (2021-2032)

8 MARKET ANALYSIS BY APPLICATION

8.1 World CSP Package eMMC Market Size Overview by Application: 2021 VS 2025 VS 2032
8.2 Segment Introduction by Application
8.2.1 Smartphones & Tablets
8.2.2 Smart TV & Set-top Boxes
8.2.3 Networking & Surveillance
8.2.4 Industrial & IoT
8.2.5 Automotive Electronics
8.2.6 Other
8.3 Market Segment by Application
8.3.1 World CSP Package eMMC Production by Application (2021-2032)
8.3.2 World CSP Package eMMC Production Value by Application (2021-2032)
8.3.3 World CSP Package eMMC Average Price by Application (2021-2032)

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9 COMPANY PROFILES

9.1 Samsung Electronics
9.1.1 Samsung Electronics Details
9.1.2 Samsung Electronics Major Business
9.1.3 Samsung Electronics CSP Package eMMC Product and Services
9.1.4 Samsung Electronics CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.1.5 Samsung Electronics Recent Developments/Updates
9.1.6 Samsung Electronics Competitive Strengths & Weaknesses
9.2 SK hynix
9.2.1 SK hynix Details
9.2.2 SK hynix Major Business
9.2.3 SK hynix CSP Package eMMC Product and Services
9.2.4 SK hynix CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.2.5 SK hynix Recent Developments/Updates
9.2.6 SK hynix Competitive Strengths & Weaknesses
9.3 Kioxia
9.3.1 Kioxia Details
9.3.2 Kioxia Major Business
9.3.3 Kioxia CSP Package eMMC Product and Services
9.3.4 Kioxia CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.3.5 Kioxia Recent Developments/Updates
9.3.6 Kioxia Competitive Strengths & Weaknesses
9.4 Sandisk
9.4.1 Sandisk Details
9.4.2 Sandisk Major Business
9.4.3 Sandisk CSP Package eMMC Product and Services
9.4.4 Sandisk CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.4.5 Sandisk Recent Developments/Updates
9.4.6 Sandisk Competitive Strengths & Weaknesses
9.5 Micron Technology
9.5.1 Micron Technology Details
9.5.2 Micron Technology Major Business
9.5.3 Micron Technology CSP Package eMMC Product and Services

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9.5.4 Micron Technology CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.5.5 Micron Technology Recent Developments/Updates
9.5.6 Micron Technology Competitive Strengths & Weaknesses
9.6 Yangtze Memory Technologies
9.6.1 Yangtze Memory Technologies Details
9.6.2 Yangtze Memory Technologies Major Business
9.6.3 Yangtze Memory Technologies CSP Package eMMC Product and Services
9.6.4 Yangtze Memory Technologies CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.6.5 Yangtze Memory Technologies Recent Developments/Updates
9.6.6 Yangtze Memory Technologies Competitive Strengths & Weaknesses
9.7 Longsys
9.7.1 Longsys Details
9.7.2 Longsys Major Business
9.7.3 Longsys CSP Package eMMC Product and Services
9.7.4 Longsys CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.7.5 Longsys Recent Developments/Updates
9.7.6 Longsys Competitive Strengths & Weaknesses
9.8 Kingston Technology
9.8.1 Kingston Technology Details
9.8.2 Kingston Technology Major Business
9.8.3 Kingston Technology CSP Package eMMC Product and Services
9.8.4 Kingston Technology CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.8.5 Kingston Technology Recent Developments/Updates
9.8.6 Kingston Technology Competitive Strengths & Weaknesses
9.9 Silicon Motion
9.9.1 Silicon Motion Details
9.9.2 Silicon Motion Major Business
9.9.3 Silicon Motion CSP Package eMMC Product and Services
9.9.4 Silicon Motion CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.9.5 Silicon Motion Recent Developments/Updates
9.9.6 Silicon Motion Competitive Strengths & Weaknesses
9.10 Macronix
9.10.1 Macronix Details
9.10.2 Macronix Major Business

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info@marketpublishers.com

9.10.3 Macronix CSP Package eMMC Product and Services
9.10.4 Macronix CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.10.5 Macronix Recent Developments/Updates
9.10.6 Macronix Competitive Strengths & Weaknesses
9.11 BIWIN
9.11.1 BIWIN Details
9.11.2 BIWIN Major Business
9.11.3 BIWIN CSP Package eMMC Product and Services
9.11.4 BIWIN CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.11.5 BIWIN Recent Developments/Updates
9.11.6 BIWIN Competitive Strengths & Weaknesses
9.12 Rayson
9.12.1 Rayson Details
9.12.2 Rayson Major Business
9.12.3 Rayson CSP Package eMMC Product and Services
9.12.4 Rayson CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.12.5 Rayson Recent Developments/Updates
9.12.6 Rayson Competitive Strengths & Weaknesses
9.13 HIKSEMI
9.13.1 HIKSEMI Details
9.13.2 HIKSEMI Major Business
9.13.3 HIKSEMI CSP Package eMMC Product and Services
9.13.4 HIKSEMI CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.13.5 HIKSEMI Recent Developments/Updates
9.13.6 HIKSEMI Competitive Strengths & Weaknesses
9.14 ADATA Technology
9.14.1 ADATA Technology Details
9.14.2 ADATA Technology Major Business
9.14.3 ADATA Technology CSP Package eMMC Product and Services
9.14.4 ADATA Technology CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.14.5 ADATA Technology Recent Developments/Updates
9.14.6 ADATA Technology Competitive Strengths & Weaknesses
9.15 Apacer Technology
9.15.1 Apacer Technology Details

+357 96 030922
info@marketpublishers.com

9.15.2 Apacer Technology Major Business
9.15.3 Apacer Technology CSP Package eMMC Product and Services
9.15.4 Apacer Technology CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.15.5 Apacer Technology Recent Developments/Updates
9.15.6 Apacer Technology Competitive Strengths & Weaknesses
9.16 Transcend Information
9.16.1 Transcend Information Details
9.16.2 Transcend Information Major Business
9.16.3 Transcend Information CSP Package eMMC Product and Services
9.16.4 Transcend Information CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.16.5 Transcend Information Recent Developments/Updates
9.16.6 Transcend Information Competitive Strengths & Weaknesses
9.17 ATP Electronics
9.17.1 ATP Electronics Details
9.17.2 ATP Electronics Major Business
9.17.3 ATP Electronics CSP Package eMMC Product and Services
9.17.4 ATP Electronics CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.17.5 ATP Electronics Recent Developments/Updates
9.17.6 ATP Electronics Competitive Strengths & Weaknesses
9.18 Greenliant
9.18.1 Greenliant Details
9.18.2 Greenliant Major Business
9.18.3 Greenliant CSP Package eMMC Product and Services
9.18.4 Greenliant CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.18.5 Greenliant Recent Developments/Updates
9.18.6 Greenliant Competitive Strengths & Weaknesses
9.19 Swissbit
9.19.1 Swissbit Details
9.19.2 Swissbit Major Business
9.19.3 Swissbit CSP Package eMMC Product and Services
9.19.4 Swissbit CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.19.5 Swissbit Recent Developments/Updates
9.19.6 Swissbit Competitive Strengths & Weaknesses
9.20 HOSIN Global Electronics

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9.20.1 HOSIN Global Electronics Details
9.20.2 HOSIN Global Electronics Major Business
9.20.3 HOSIN Global Electronics CSP Package eMMC Product and Services
9.20.4 HOSIN Global Electronics CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.20.5 HOSIN Global Electronics Recent Developments/Updates
9.20.6 HOSIN Global Electronics Competitive Strengths & Weaknesses
9.21 SCY
9.21.1 SCY Details
9.21.2 SCY Major Business
9.21.3 SCY CSP Package eMMC Product and Services
9.21.4 SCY CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.21.5 SCY Recent Developments/Updates
9.21.6 SCY Competitive Strengths & Weaknesses
9.22 KOWIN Technology
9.22.1 KOWIN Technology Details
9.22.2 KOWIN Technology Major Business
9.22.3 KOWIN Technology CSP Package eMMC Product and Services
9.22.4 KOWIN Technology CSP Package eMMC Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.22.5 KOWIN Technology Recent Developments/Updates
9.22.6 KOWIN Technology Competitive Strengths & Weaknesses

10 INDUSTRY CHAIN ANALYSIS

10.1 CSP Package eMMC Industry Chain
10.2 CSP Package eMMC Upstream Analysis
10.2.1 CSP Package eMMC Core Raw Materials
10.2.2 Main Manufacturers of CSP Package eMMC Core Raw Materials
10.3 Midstream Analysis
10.4 Downstream Analysis
10.5 CSP Package eMMC Production Mode
10.6 CSP Package eMMC Procurement Model
10.7 CSP Package eMMC Industry Sales Model and Sales Channels
10.7.1 CSP Package eMMC Sales Model
10.7.2 CSP Package eMMC Typical Distributors

11 RESEARCH FINDINGS AND CONCLUSION

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12 APPENDIX

12.1 Methodology
12.2 Research Process and Data Source
12.3 Disclaimer

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List Of Tables

LIST OF TABLES

Table 1. World CSP Package eMMC Production Value by Region (2021, 2025 and 2032) & (USD Million)
Table 2. World CSP Package eMMC Production Value by Region (2021-2026) & (USD Million)
Table 3. World CSP Package eMMC Production Value by Region (2027-2032) & (USD Million)
Table 4. World CSP Package eMMC Production Value Market Share by Region (2021-2026)
Table 5. World CSP Package eMMC Production Value Market Share by Region (2027-2032)
Table 6. World CSP Package eMMC Production by Region (2021-2026) & (Million Units)
Table 7. World CSP Package eMMC Production by Region (2027-2032) & (Million Units)
Table 8. World CSP Package eMMC Production Market Share by Region (2021-2026)
Table 9. World CSP Package eMMC Production Market Share by Region (2027-2032)
Table 10. World CSP Package eMMC Average Price by Region (2021-2026) & (US$/Unit)
Table 11. World CSP Package eMMC Average Price by Region (2027-2032) & (US$/Unit)
Table 12. CSP Package eMMC Major Market Trends
Table 13. World CSP Package eMMC Consumption Growth Rate Forecast by Region (2021 & 2025 & 2032) & (Million Units)
Table 14. World CSP Package eMMC Consumption by Region (2021-2026) & (Million Units)
Table 15. World CSP Package eMMC Consumption Forecast by Region (2027-2032) & (Million Units)
Table 16. World CSP Package eMMC Production Value by Manufacturer (2021-2026) & (USD Million)
Table 17. Production Value Market Share of Key CSP Package eMMC Producers in 2025
Table 18. World CSP Package eMMC Production by Manufacturer (2021-2026) & (Million Units)
Table 19. Production Market Share of Key CSP Package eMMC Producers in 2025
Table 20. World CSP Package eMMC Average Price by Manufacturer (2021-2026) &

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(US$/Unit)
Table 21. Global CSP Package eMMC Company Evaluation Quadrant
Table 22. World CSP Package eMMC Industry Rank of Major Manufacturers, Based on Production Value in 2025
Table 23. Head Office and CSP Package eMMC Production Site of Key Manufacturer
Table 24. CSP Package eMMC Market: Company Product Type Footprint
Table 25. CSP Package eMMC Market: Company Product Application Footprint
Table 26. CSP Package eMMC Competitive Factors
Table 27. CSP Package eMMC New Entrant and Capacity Expansion Plans
Table 28. CSP Package eMMC Mergers & Acquisitions Activity
Table 29. United States VS China CSP Package eMMC Production Value Comparison, (2021 & 2025 & 2032) & (USD Million)
Table 30. United States VS China CSP Package eMMC Production Comparison, (2021 & 2025 & 2032) & (Million Units)
Table 31. United States VS China CSP Package eMMC Consumption Comparison, (2021 & 2025 & 2032) & (Million Units)
Table 32. United States Based CSP Package eMMC Manufacturers, Headquarters and Production Site (States, Country)
Table 33. United States Based Manufacturers CSP Package eMMC Production Value, (2021-2026) & (USD Million)
Table 34. United States Based Manufacturers CSP Package eMMC Production Value Market Share (2021-2026)
Table 35. United States Based Manufacturers CSP Package eMMC Production (2021-2026) & (Million Units)
Table 36. United States Based Manufacturers CSP Package eMMC Production Market Share (2021-2026)
Table 37. China Based CSP Package eMMC Manufacturers, Headquarters and Production Site (Province, Country)
Table 38. China Based Manufacturers CSP Package eMMC Production Value, (2021-2026) & (USD Million)
Table 39. China Based Manufacturers CSP Package eMMC Production Value Market Share (2021-2026)
Table 40. China Based Manufacturers CSP Package eMMC Production, (2021-2026) & (Million Units)
Table 41. China Based Manufacturers CSP Package eMMC Production Market Share (2021-2026)
Table 42. Rest of World Based CSP Package eMMC Manufacturers, Headquarters and Production Site (State, Country)
Table 43. Rest of World Based Manufacturers CSP Package eMMC Production Value,

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(2021-2026) & (USD Million)
Table 44. Rest of World Based Manufacturers CSP Package eMMC Production Value Market Share (2021-2026)
Table 45. Rest of World Based Manufacturers CSP Package eMMC Production, (2021-2026) & (Million Units)
Table 46. Rest of World Based Manufacturers CSP Package eMMC Production Market Share (2021-2026)
Table 47. World CSP Package eMMC Production Value by Type, (USD Million), 2021 & 2025 & 2032
Table 48. World CSP Package eMMC Production by Type (2021-2026) & (Million Units)
Table 49. World CSP Package eMMC Production by Type (2027-2032) & (Million Units)
Table 50. World CSP Package eMMC Production Value by Type (2021-2026) & (USD Million)
Table 51. World CSP Package eMMC Production Value by Type (2027-2032) & (USD Million)
Table 52. World CSP Package eMMC Average Price by Type (2021-2026) & (US$/Unit)
Table 53. World CSP Package eMMC Average Price by Type (2027-2032) & (US$/Unit)
Table 54. World CSP Package eMMC Production Value by Package Configuration, (USD Million), 2021 & 2025 & 2032
Table 55. World CSP Package eMMC Production by Package Configuration (2021-2026) & (Million Units)
Table 56. World CSP Package eMMC Production by Package Configuration (2027-2032) & (Million Units)
Table 57. World CSP Package eMMC Production Value by Package Configuration (2021-2026) & (USD Million)
Table 58. World CSP Package eMMC Production Value by Package Configuration (2027-2032) & (USD Million)
Table 59. World CSP Package eMMC Average Price by Package Configuration (2021-2026) & (US$/Unit)
Table 60. World CSP Package eMMC Average Price by Package Configuration (2027-2032) & (US$/Unit)
Table 61. World CSP Package eMMC Production Value by Product Grade, (USD Million), 2021 & 2025 & 2032
Table 62. World CSP Package eMMC Production by Product Grade (2021-2026) & (Million Units)
Table 63. World CSP Package eMMC Production by Product Grade (2027-2032) & (Million Units)
Table 64. World CSP Package eMMC Production Value by Product Grade (2021-2026) & (USD Million)

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Table 65. World CSP Package eMMC Production Value by Product Grade (2027-2032) & (USD Million)
Table 66. World CSP Package eMMC Average Price by Product Grade (2021-2026) & (US$/Unit)
Table 67. World CSP Package eMMC Average Price by Product Grade (2027-2032) & (US$/Unit)
Table 68. World CSP Package eMMC Production Value by Application, (USD Million), 2021 & 2025 & 2032
Table 69. World CSP Package eMMC Production by Application (2021-2026) & (Million Units)
Table 70. World CSP Package eMMC Production by Application (2027-2032) & (Million Units)
Table 71. World CSP Package eMMC Production Value by Application (2021-2026) & (USD Million)
Table 72. World CSP Package eMMC Production Value by Application (2027-2032) & (USD Million)
Table 73. World CSP Package eMMC Average Price by Application (2021-2026) & (US$/Unit)
Table 74. World CSP Package eMMC Average Price by Application (2027-2032) & (US$/Unit)
Table 75. Samsung Electronics Basic Information, Manufacturing Base and Competitors
Table 76. Samsung Electronics Major Business
Table 77. Samsung Electronics CSP Package eMMC Product and Services
Table 78. Samsung Electronics CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 79. Samsung Electronics Recent Developments/Updates
Table 80. Samsung Electronics Competitive Strengths & Weaknesses
Table 81. SK hynix Basic Information, Manufacturing Base and Competitors
Table 82. SK hynix Major Business
Table 83. SK hynix CSP Package eMMC Product and Services
Table 84. SK hynix CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 85. SK hynix Recent Developments/Updates
Table 86. SK hynix Competitive Strengths & Weaknesses
Table 87. Kioxia Basic Information, Manufacturing Base and Competitors
Table 88. Kioxia Major Business
Table 89. Kioxia CSP Package eMMC Product and Services
Table 90. Kioxia CSP Package eMMC Production (Million Units), Price (US$/Unit),

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Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 91. Kioxia Recent Developments/Updates
Table 92. Kioxia Competitive Strengths & Weaknesses
Table 93. Sandisk Basic Information, Manufacturing Base and Competitors
Table 94. Sandisk Major Business
Table 95. Sandisk CSP Package eMMC Product and Services
Table 96. Sandisk CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 97. Sandisk Recent Developments/Updates
Table 98. Sandisk Competitive Strengths & Weaknesses
Table 99. Micron Technology Basic Information, Manufacturing Base and Competitors
Table 100. Micron Technology Major Business
Table 101. Micron Technology CSP Package eMMC Product and Services
Table 102. Micron Technology CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 103. Micron Technology Recent Developments/Updates
Table 104. Micron Technology Competitive Strengths & Weaknesses
Table 105. Yangtze Memory Technologies Basic Information, Manufacturing Base and Competitors
Table 106. Yangtze Memory Technologies Major Business
Table 107. Yangtze Memory Technologies CSP Package eMMC Product and Services
Table 108. Yangtze Memory Technologies CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 109. Yangtze Memory Technologies Recent Developments/Updates
Table 110. Yangtze Memory Technologies Competitive Strengths & Weaknesses
Table 111. Longsys Basic Information, Manufacturing Base and Competitors
Table 112. Longsys Major Business
Table 113. Longsys CSP Package eMMC Product and Services
Table 114. Longsys CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 115. Longsys Recent Developments/Updates
Table 116. Longsys Competitive Strengths & Weaknesses
Table 117. Kingston Technology Basic Information, Manufacturing Base and Competitors
Table 118. Kingston Technology Major Business
Table 119. Kingston Technology CSP Package eMMC Product and Services
Table 120. Kingston Technology CSP Package eMMC Production (Million Units), Price

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(US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 121. Kingston Technology Recent Developments/Updates
Table 122. Kingston Technology Competitive Strengths & Weaknesses
Table 123. Silicon Motion Basic Information, Manufacturing Base and Competitors
Table 124. Silicon Motion Major Business
Table 125. Silicon Motion CSP Package eMMC Product and Services
Table 126. Silicon Motion CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 127. Silicon Motion Recent Developments/Updates
Table 128. Silicon Motion Competitive Strengths & Weaknesses
Table 129. Macronix Basic Information, Manufacturing Base and Competitors
Table 130. Macronix Major Business
Table 131. Macronix CSP Package eMMC Product and Services
Table 132. Macronix CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 133. Macronix Recent Developments/Updates
Table 134. Macronix Competitive Strengths & Weaknesses
Table 135. BIWIN Basic Information, Manufacturing Base and Competitors
Table 136. BIWIN Major Business
Table 137. BIWIN CSP Package eMMC Product and Services
Table 138. BIWIN CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 139. BIWIN Recent Developments/Updates
Table 140. BIWIN Competitive Strengths & Weaknesses
Table 141. Rayson Basic Information, Manufacturing Base and Competitors
Table 142. Rayson Major Business
Table 143. Rayson CSP Package eMMC Product and Services
Table 144. Rayson CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 145. Rayson Recent Developments/Updates
Table 146. Rayson Competitive Strengths & Weaknesses
Table 147. HIKSEMI Basic Information, Manufacturing Base and Competitors
Table 148. HIKSEMI Major Business
Table 149. HIKSEMI CSP Package eMMC Product and Services
Table 150. HIKSEMI CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 151. HIKSEMI Recent Developments/Updates

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Table 152. HIKSEMI Competitive Strengths & Weaknesses
Table 153. ADATA Technology Basic Information, Manufacturing Base and Competitors
Table 154. ADATA Technology Major Business
Table 155. ADATA Technology CSP Package eMMC Product and Services
Table 156. ADATA Technology CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 157. ADATA Technology Recent Developments/Updates
Table 158. ADATA Technology Competitive Strengths & Weaknesses
Table 159. Apacer Technology Basic Information, Manufacturing Base and Competitors
Table 160. Apacer Technology Major Business
Table 161. Apacer Technology CSP Package eMMC Product and Services
Table 162. Apacer Technology CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 163. Apacer Technology Recent Developments/Updates
Table 164. Apacer Technology Competitive Strengths & Weaknesses
Table 165. Transcend Information Basic Information, Manufacturing Base and Competitors
Table 166. Transcend Information Major Business
Table 167. Transcend Information CSP Package eMMC Product and Services
Table 168. Transcend Information CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 169. Transcend Information Recent Developments/Updates
Table 170. Transcend Information Competitive Strengths & Weaknesses
Table 171. ATP Electronics Basic Information, Manufacturing Base and Competitors
Table 172. ATP Electronics Major Business
Table 173. ATP Electronics CSP Package eMMC Product and Services
Table 174. ATP Electronics CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 175. ATP Electronics Recent Developments/Updates
Table 176. ATP Electronics Competitive Strengths & Weaknesses
Table 177. Greenliant Basic Information, Manufacturing Base and Competitors
Table 178. Greenliant Major Business
Table 179. Greenliant CSP Package eMMC Product and Services
Table 180. Greenliant CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

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Table 181. Greenliant Recent Developments/Updates
Table 182. Greenliant Competitive Strengths & Weaknesses
Table 183. Swissbit Basic Information, Manufacturing Base and Competitors
Table 184. Swissbit Major Business
Table 185. Swissbit CSP Package eMMC Product and Services
Table 186. Swissbit CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 187. Swissbit Recent Developments/Updates
Table 188. Swissbit Competitive Strengths & Weaknesses
Table 189. HOSIN Global Electronics Basic Information, Manufacturing Base and Competitors
Table 190. HOSIN Global Electronics Major Business
Table 191. HOSIN Global Electronics CSP Package eMMC Product and Services
Table 192. HOSIN Global Electronics CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 193. HOSIN Global Electronics Recent Developments/Updates
Table 194. HOSIN Global Electronics Competitive Strengths & Weaknesses
Table 195. SCY Basic Information, Manufacturing Base and Competitors
Table 196. SCY Major Business
Table 197. SCY CSP Package eMMC Product and Services
Table 198. SCY CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 199. SCY Recent Developments/Updates
Table 200. SCY Competitive Strengths & Weaknesses
Table 201. KOWIN Technology Basic Information, Manufacturing Base and Competitors
Table 202. KOWIN Technology Major Business
Table 203. KOWIN Technology CSP Package eMMC Product and Services
Table 204. KOWIN Technology CSP Package eMMC Production (Million Units), Price (US$/Unit), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 205. KOWIN Technology Recent Developments/Updates
Table 206. KOWIN Technology Competitive Strengths & Weaknesses
Table 207. Global Key Players of CSP Package eMMC Upstream (Raw Materials)
Table 208. Global CSP Package eMMC Typical Customers
Table 209. CSP Package eMMC Typical Distributors

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List Of Figures

LIST OF FIGURES

Figure 1. CSP Package eMMC Picture
Figure 2. World CSP Package eMMC Production Value: 2021 & 2025 & 2032, (USD Million)
Figure 3. World CSP Package eMMC Production Value and Forecast (2021-2032) & (USD Million)
Figure 4. World CSP Package eMMC Production (2021-2032) & (Million Units)
Figure 5. World CSP Package eMMC Average Price (2021-2032) & (US$/Unit)
Figure 6. World CSP Package eMMC Production Value Market Share by Region (2021-2032)
Figure 7. World CSP Package eMMC Production Market Share by Region (2021-2032)
Figure 8. North America CSP Package eMMC Production (2021-2032) & (Million Units)
Figure 9. Europe CSP Package eMMC Production (2021-2032) & (Million Units)
Figure 10. China CSP Package eMMC Production (2021-2032) & (Million Units)
Figure 11. Japan CSP Package eMMC Production (2021-2032) & (Million Units)
Figure 12. South Korea CSP Package eMMC Production (2021-2032) & (Million Units)
Figure 13. CSP Package eMMC Market Drivers
Figure 14. Factors Affecting Demand
Figure 15. World CSP Package eMMC Consumption (2021-2032) & (Million Units)
Figure 16. World CSP Package eMMC Consumption Market Share by Region (2021-2032)
Figure 17. United States CSP Package eMMC Consumption (2021-2032) & (Million Units)
Figure 18. China CSP Package eMMC Consumption (2021-2032) & (Million Units)
Figure 19. Europe CSP Package eMMC Consumption (2021-2032) & (Million Units)
Figure 20. Japan CSP Package eMMC Consumption (2021-2032) & (Million Units)
Figure 21. South Korea CSP Package eMMC Consumption (2021-2032) & (Million Units)
Figure 22. ASEAN CSP Package eMMC Consumption (2021-2032) & (Million Units)
Figure 23. India CSP Package eMMC Consumption (2021-2032) & (Million Units)
Figure 24. Producer Shipments of CSP Package eMMC by Manufacturer Revenue ($MM) and Market Share (%): 2025
Figure 25. Global Four-firm Concentration Ratios (CR4) for CSP Package eMMC Markets in 2025
Figure 26. Global Four-firm Concentration Ratios (CR8) for CSP Package eMMC Markets in 2025

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Figure 27. United States VS China: CSP Package eMMC Production Value Market Share Comparison (2021 & 2025 & 2032)
Figure 28. United States VS China: CSP Package eMMC Production Market Share Comparison (2021 & 2025 & 2032)
Figure 29. United States VS China: CSP Package eMMC Consumption Market Share Comparison (2021 & 2025 & 2032)
Figure 30. United States Based Manufacturers CSP Package eMMC Production Market Share 2025
Figure 31. China Based Manufacturers CSP Package eMMC Production Market Share 2025
Figure 32. Rest of World Based Manufacturers CSP Package eMMC Production Market Share 2025
Figure 33. World CSP Package eMMC Production Value by Type, (USD Million), 2021 & 2025 & 2032
Figure 34. World CSP Package eMMC Production Value Market Share by Type in 2025
Figure 35. 8GB and Below
Figure 36. 16GB
Figure 37. 32GB
Figure 38. 64GB
Figure 39. 128GB
Figure 40. 256GB and Above
Figure 41. World CSP Package eMMC Production Market Share by Type (2021-2032)
Figure 42. World CSP Package eMMC Production Value Market Share by Type (2021-2032)
Figure 43. World CSP Package eMMC Average Price by Type (2021-2032) & (US$/Unit)
Figure 44. World CSP Package eMMC Production Value by Package Configuration, (USD Million), 2021 & 2025 & 2032
Figure 45. World CSP Package eMMC Production Value Market Share by Package Configuration in 2025
Figure 46. Standard 153-ball BGA
Figure 47. Compact BGA
Figure 48. 100-ball BGA
Figure 49. Other
Figure 50. World CSP Package eMMC Production Market Share by Package Configuration (2021-2032)
Figure 51. World CSP Package eMMC Production Value Market Share by Package Configuration (2021-2032)
Figure 52. World CSP Package eMMC Average Price by Package Configuration

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(2021-2032) & (US$/Unit)
Figure 53. World CSP Package eMMC Production Value by Product Grade, (USD Million), 2021 & 2025 & 2032
Figure 54. World CSP Package eMMC Production Value Market Share by Product Grade in 2025
Figure 55. Commercial Grade
Figure 56. Industrial Grade
Figure 57. Automotive Grade
Figure 58. World CSP Package eMMC Production Market Share by Product Grade (2021-2032)
Figure 59. World CSP Package eMMC Production Value Market Share by Product Grade (2021-2032)
Figure 60. World CSP Package eMMC Average Price by Product Grade (2021-2032) & (US$/Unit)
Figure 61. World CSP Package eMMC Production Value by Application, (USD Million), 2021 & 2025 & 2032
Figure 62. World CSP Package eMMC Production Value Market Share by Application in 2025
Figure 63. Smartphones & Tablets
Figure 64. Smart TV & Set-top Boxes
Figure 65. Networking & Surveillance
Figure 66. Industrial & IoT
Figure 67. Automotive Electronics
Figure 68. Other
Figure 69. World CSP Package eMMC Production Market Share by Application (2021-2032)
Figure 70. World CSP Package eMMC Production Value Market Share by Application (2021-2032)
Figure 71. World CSP Package eMMC Average Price by Application (2021-2032) & (US$/Unit)
Figure 72. CSP Package eMMC Industry Chain
Figure 73. CSP Package eMMC Procurement Model
Figure 74. CSP Package eMMC Sales Model
Figure 75. CSP Package eMMC Sales Channels, Direct Sales, and Distribution
Figure 76. Methodology
Figure 77. Research Process and Data Source

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